

RoHS Compliant Product
A Suffix of "-C" specifies halogen & lead-free

FEATURES

- Low On-Resistance
- Fast Switching Speed
- Low-Voltage Drive
- Easily Designed Drive Circuits
- ESD Protected: 2KV

MARKING

RS

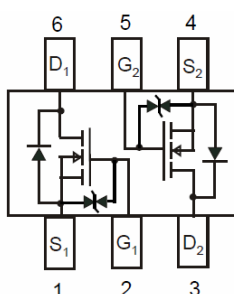
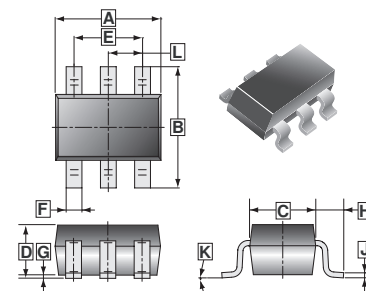
PACKAGE INFORMATION

Package	MPQ	Leader Size
SOT-363	3K	7 inch

ORDER INFORMATION

Part Number	Type
S2N7002KDW	Lead (Pb)-free
S2N7002KDW-C	Lead (Pb)-free and Halogen-free

SOT-363



REF.	Millimeter		REF.	Millimeter	
	Min.	Max.		Min.	Max.
A	1.80	2.20	G	0.100	REF.
B	1.80	2.45	H	0.525	REF.
C	1.15	1.35	J	0.08	0.25
D	0.80	1.10	K		8°
E	1.10	1.50	L	0.650	TYP.
F	0.10	0.35			

MAXIMUM RATINGS (T_A=25°C unless otherwise specified)

Parameter	Symbol	Ratings	Unit
Drain-Source Voltage	V _{DSS}	60	V
Gate-Source Voltage	V _{GSS}	±20	V
Continuous Drain Current	I _D	115	mA
Pulsed Drain Current ¹	I _{DP}	800	mA
Continuous Reverse Drain Current	I _{DR}	115	mA
Pulsed Reverse Drain Current ¹	I _{DRP}	800	mA
Total Power Dissipation ²	P _D	225	mW
Operating Junction & Storage Temperature Range	T _J , T _{STG}	-55~150	°C

ELECTRICAL CHARACTERISTICS (T_A=25°C unless otherwise specified)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Test Conditions
Drain-Source Breakdown Voltage	V _{(BR)DSS}	60	-	-	V	V _{GS} =0, I _D =10μA
Zero Gate Voltage Drain Current	I _{DSS}	-	-	1	μA	V _{DS} =60V, V _{GS} =0
Gate-Source Leakage	I _{GSS}	-	-	±10	μA	V _{DS} =0, V _{GS} = ±20V
Gate Threshold Voltage	V _{GS(th)}	1	1.85	2.5	V	V _{DS} =10V, I _D =1mA
Static Drain-Source On-Resistance	R _{DS(ON)}	-	-	7.5	Ω	V _{GS} =10V, I _D =0.5A
		-	-	8.5		V _{GS} =4.5V, I _D =0.2A
Forward Transfer Admittance ³	g _{fs}	-	80	-	mS	V _{DS} =10V, I _D =0.2A
Turn-on Delay Time ³	T _{d(on)}	-	12	-	nS	I _D =0.2A, V _{DD} =30V V _{GS} =10V, R _L =103Ω R _G =6Ω
Turn-on Rise Time ³	T _{r(on)}	-	14	-		
Turn-off Delay Time ³	T _{d(off)}	-	20	-		
Turn-off Fall Time ³	T _{r(off)}	-	22	-		
Input Capacitance	C _{iss}	-	25	-	pF	V _{DS} =25V V _{GS} =0 f=1MHz
Output Capacitance	C _{oss}	-	10	-		
Reverse Transfer Capacitance	C _{rss}	-	3	-		

Notes:

1. P_w ≤ 10μs, Duty cycle ≤ 1%.
2. When mounted on a 1x0.75x0.062 inch glass epoxy board.
3. P_w ≤ 300μs, Duty cycle ≤ 1%.

CHARACTERISTIC CURVES

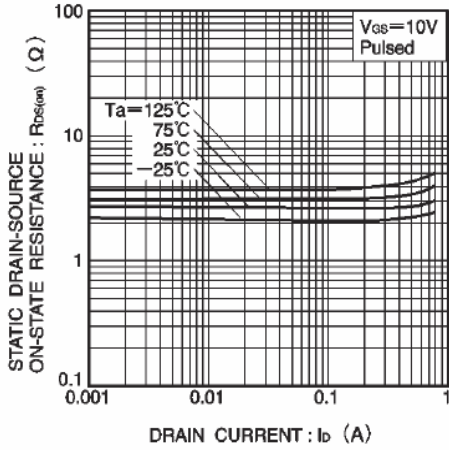


Fig. 1 Static drain-source on-state resistance vs. drain current (I)

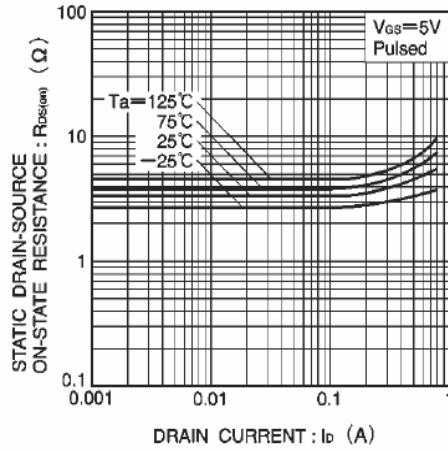


Fig. 2 Static drain-source on-state resistance vs. drain current (II)

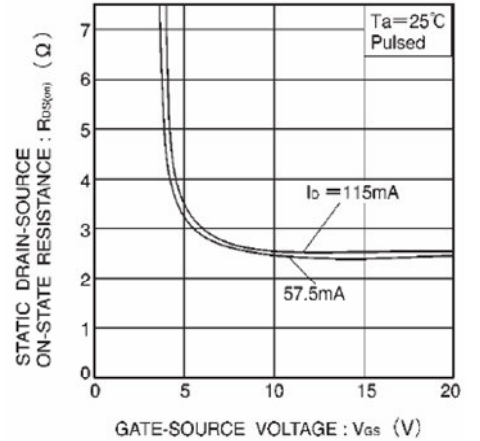


Fig. 3 Static drain-source on-state resistance vs. gate-source voltage

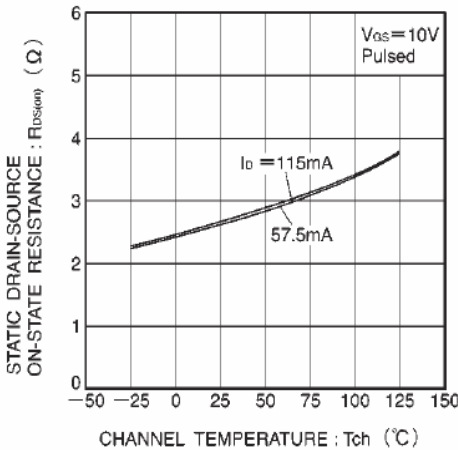


Fig. 4 Static drain-source on-state resistance vs. channel temperature

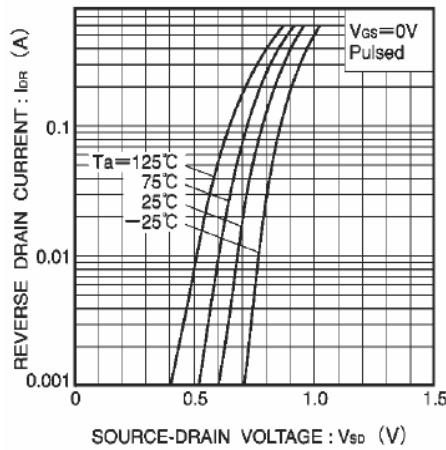


Fig. 5 Reverse drain current vs. source-drain voltage (I)

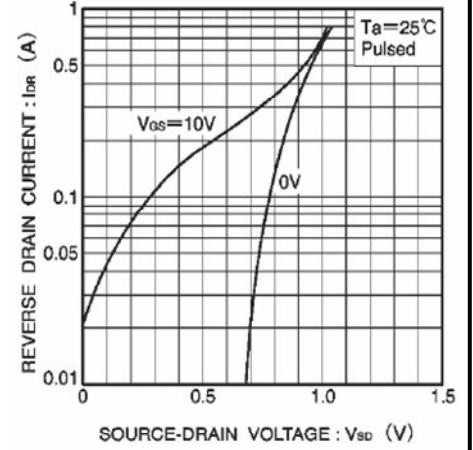


Fig. 6 Reverse drain current vs. source-drain voltage (II)

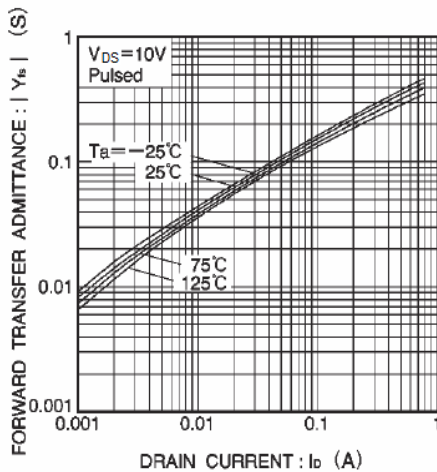


Fig. 7 Forward transfer admittance vs. drain current

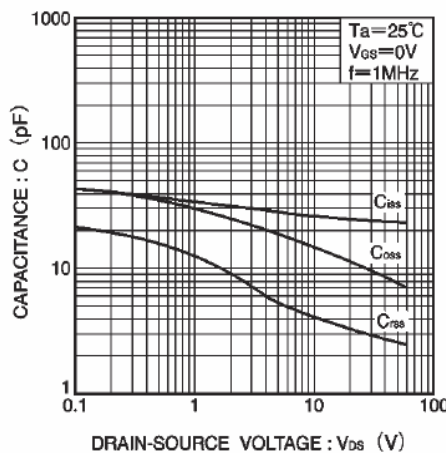


Fig. 8 Typical capacitance vs. drain-source voltage

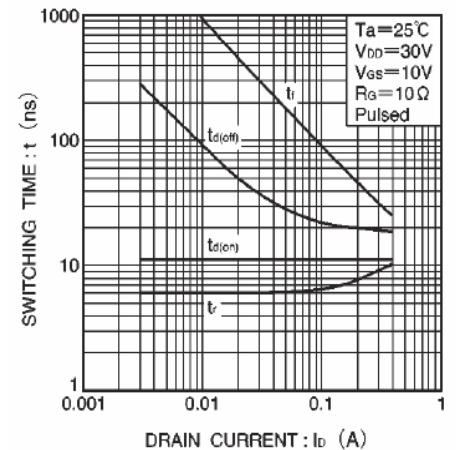


Fig. 9 Switching characteristics